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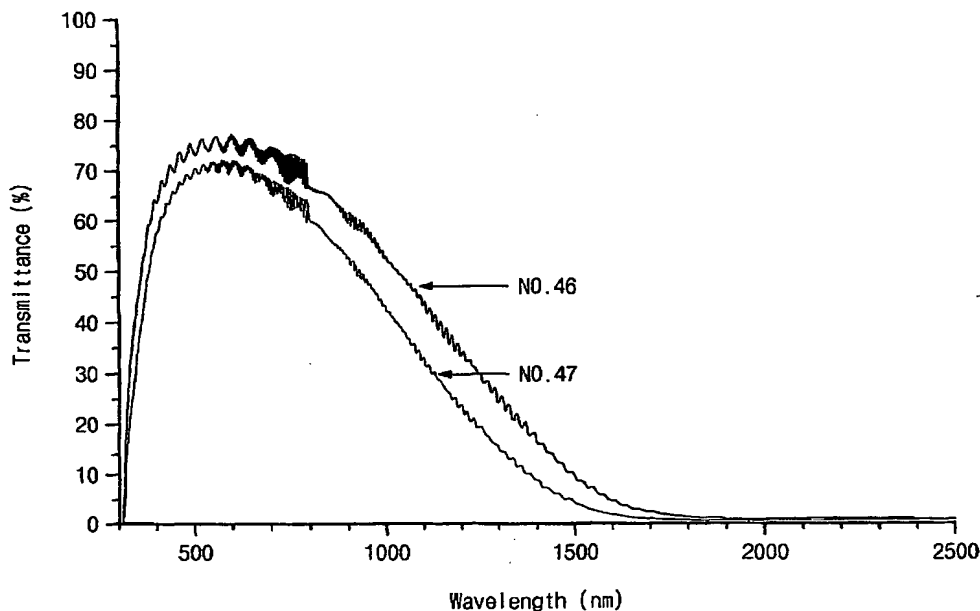
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(54) Title: COMPOSITION FOR CUTTING OFF HEAT-RAY, FILM FORMED THEREFROM AND METHOD FOR FORMING THE COMPOSITION AND THE FILM



(57) Abstract: Disclosed are heat-ray cutoff compounds, films and method using them. The heat-ray compound is produced by dispersing conductive nanoparticles in an amphoteric solvent with acids and dispersion sol, which provides a low cost production for the heat-ray cutoff films because it is able to any resin binder without sorting the kinds of resin binders (hydrolic or alcoholic, or anti-hydrolic).

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